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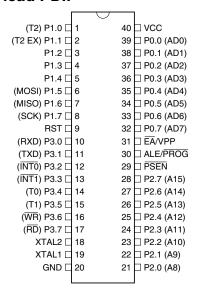
Applications of "<u>Embedded - Microcontrollers</u>"

Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89s52-24aur
Supplier Device Package	44-TQFP (10x10)
Package / Case	44-TQFP
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Oscillator Type	Internal
Data Converters	-
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
RAM Size	256 x 8
EEPROM Size	-
Program Memory Type	FLASH
Program Memory Size	8KB (8K x 8)
Number of I/O	32
Peripherals	WDT
Connectivity	UART/USART
Speed	24MHz
Core Size	8-Bit
Core Processor	8051
Product Status	Active
Details	

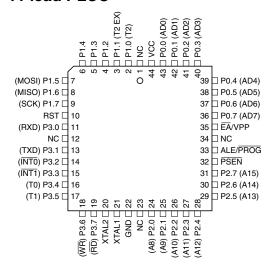


2. Pin Configurations

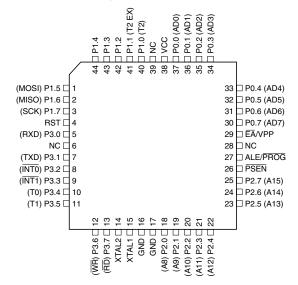
2.1 40-lead PDIP



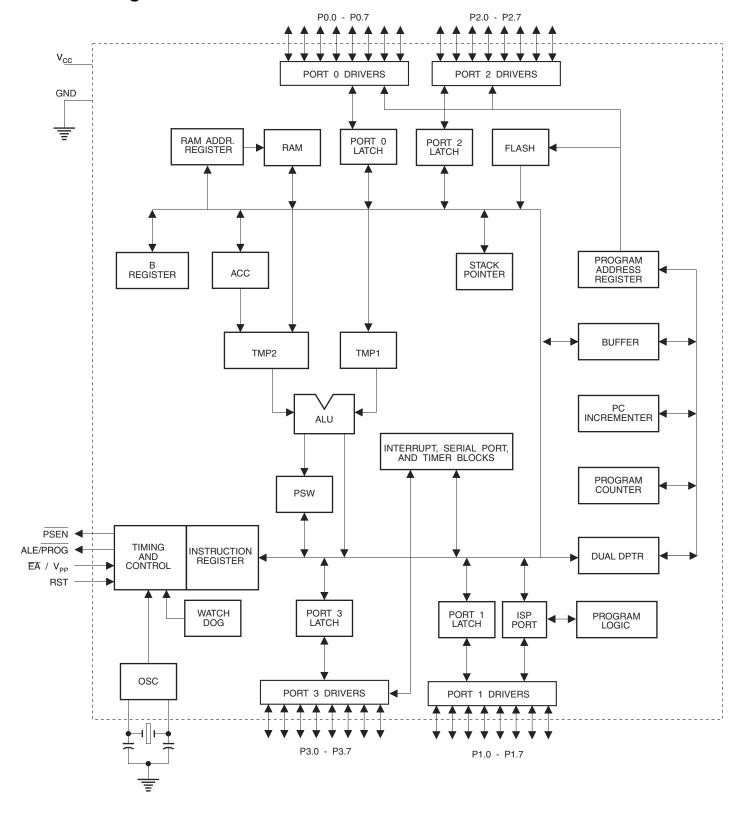
2.3 44-lead PLCC



2.2 44-lead TQFP



3. Block Diagram





4.6 Port 3

Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}) because of the pull-ups.

Port 3 receives some control signals for Flash programming and verification.

Port 3 also serves the functions of various special features of the AT89S52, as shown in the following table.

Port Pin	Alternate Functions
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	ĪNTŌ (external interrupt 0)
P3.3	INT1 (external interrupt 1)
P3.4	T0 (timer 0 external input)
P3.5	T1 (timer 1 external input)
P3.6	WR (external data memory write strobe)
P3.7	RD (external data memory read strobe)

4.7 RST

Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device. This pin drives high for 98 oscillator periods after the Watchdog times out. The DISRTO bit in SFR AUXR (address 8EH) can be used to disable this feature. In the default state of bit DISRTO, the RESET HIGH out feature is enabled.

4.8 ALE/PROG

Address Latch Enable (ALE) is an output pulse for latching the low byte of the address during accesses to external memory. This pin is also the program pulse input (PROG) during Flash programming.

In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external data memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX or MOVC instruction. Otherwise, the pin is weakly pulled high. Setting the ALE-disable bit has no effect if the microcontroller is in external execution mode.





4.9 PSEN

Program Store Enable (PSEN) is the read strobe to external program memory.

When the AT89S52 is executing code from external program memory, $\overline{\text{PSEN}}$ is activated twice each machine cycle, except that two $\overline{\text{PSEN}}$ activations are skipped during each access to external data memory.

4.10 **EA/VPP**

External Access Enable. $\overline{\mathsf{EA}}$ must be strapped to GND in order to enable the device to fetch code from external program memory locations starting at 0000H up to FFFFH. Note, however, that if lock bit 1 is programmed, $\overline{\mathsf{EA}}$ will be internally latched on reset.

 $\overline{\sf EA}$ should be strapped to $V_{\sf CC}$ for internal program executions.

This pin also receives the 12-volt programming enable voltage (V_{PP}) during Flash programming.

4.11 XTAL1

Input to the inverting oscillator amplifier and input to the internal clock operating circuit.

4.12 XTAL2

Output from the inverting oscillator amplifier.

5. Special Function Registers

A map of the on-chip memory area called the Special Function Register (SFR) space is shown in Table 5-1.

Note that not all of the addresses are occupied, and unoccupied addresses may not be implemented on the chip. Read accesses to these addresses will in general return random data, and write accesses will have an indeterminate effect.

User software should not write 1s to these unlisted locations, since they may be used in future products to invoke new features. In that case, the reset or inactive values of the new bits will always be 0.

Timer 2 Registers: Control and status bits are contained in registers T2CON (shown in Table 5-2) and T2MOD (shown in Table 10-2) for Timer 2. The register pair (RCAP2H, RCAP2L) are the Capture/Reload registers for Timer 2 in 16-bit capture mode or 16-bit auto-reload mode.

Interrupt Registers: The individual interrupt enable bits are in the IE register. Two priorities can be set for each of the six interrupt sources in the IP register.



 Table 5-2.
 T2CON – Timer/Counter 2 Control Register

T2CON	Address = 00	C8H		Reset Value = 0000 0000B						
Bit Add	ressable									
D:4	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/RL2		
Bit	7	6	5	4	3	2	1	0		

Symbol	Function
TF2	Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK = 1 or TCLK = 1.
EXF2	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software. EXF2 does not cause an interrupt in up/down counter mode (DCEN = 1).
RCLK	Receive clock enable. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in serial port Modes 1 and 3. RCLK = 0 causes Timer 1 overflow to be used for the receive clock.
TCLK	Transmit clock enable. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in serial port Modes 1 and 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.
EXEN2	Timer 2 external enable. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.
TR2	Start/Stop control for Timer 2. TR2 = 1 starts the timer.
C/T2	Timer or counter select for Timer 2. $C/\overline{T2} = 0$ for timer function. $C/\overline{T2} = 1$ for external event counter (falling edge triggered).
CP/RL2	Capture/Reload select. $CP/\overline{RL2} = 1$ causes captures to occur on negative transitions at T2EX if EXEN2 = 1. $CP/\overline{RL2} = 0$ causes automatic reloads to occur when Timer 2 overflows or negative transitions occur at T2EX when EXEN2 = 1. When either RCLK or TCLK = 1, this bit is ignored and the timer is forced to auto-reload on Timer 2 overflow.

Table 5-3. AUXR: Auxiliary Register

AUXR	Address = 8EH Reset Value = XXX00XX0B										
	Not Bit Addressable										
		_	_	_	WDIDLE	DISRTO	_	_	DISALE		
	Bit	7	6	5	4	3	2	1	0		
_	Reserved for	r future expa	ınsion								
DISALE	Disable/Enal	ble ALE									
	DISALE	Operating	Mode								
	0	ALE is emitted at a constant rate of 1/6 the oscillator frequency									
	1	ALE is act	ive only dur	ing a MOV	X or MOVC ir	struction					
DISRTO	Disable/Enal	ble Reset ou	ıt								
	DISRTO										
	0	Reset pin	is driven Hi	gh after WD	T times out						
	1	Reset pin	is input only	/							
WDIDLE	Disable/Enal	ble WDT in I	DLE mode								
	WDIDLE										
	0	WDT cont	inues to cou	unt in IDLE	mode						
	1	WDT halts	counting ir	n IDLE mod	е						

Dual Data Pointer Registers: To facilitate accessing both internal and external data memory, two banks of 16-bit Data Pointer Registers are provided: DP0 at SFR address locations 82H-83H and DP1 at 84H-85H. Bit DPS = 0 in SFR AUXR1 selects DP0 and DPS = 1 selects DP1. The user should **ALWAYS** initialize the DPS bit to the appropriate value before accessing the respective Data Pointer Register.

Power Off Flag: The Power Off Flag (POF) is located at bit 4 (PCON.4) in the PCON SFR. POF is set to "1" during power up. It can be set and rest under software control and is not affected by reset.

Table 5-4. AUXR1: Auxiliary Register 1

AUXR1	Address	= A2H			Reset Value = XXXXXXX0B						
	Not Bit A	Not Bit Addressable									
		_	_	_	_	_	_	_	DPS		
	Bit	7	6	5	4	3	2	1	0		
_	Reserved for	future expa	ansion								
DPS	Data Pointer	Register Se	elect								
	DPS										
	0	Selects D	PTR Regist	ers DP0L, D	P0H						
	1	Selects D	PTR Regist	ers DP1L, D	P1H						





6. Memory Organization

MCS-51 devices have a separate address space for Program and Data Memory. Up to 64K bytes each of external Program and Data Memory can be addressed.

6.1 Program Memory

If the EA pin is connected to GND, all program fetches are directed to external memory.

On the AT89S52, if $\overline{\text{EA}}$ is connected to V_{CC} , program fetches to addresses 0000H through 1FFFH are directed to internal memory and fetches to addresses 2000H through FFFFH are to external memory.

6.2 Data Memory

The AT89S52 implements 256 bytes of on-chip RAM. The upper 128 bytes occupy a parallel address space to the Special Function Registers. This means that the upper 128 bytes have the same addresses as the SFR space but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the address mode used in the instruction specifies whether the CPU accesses the upper 128 bytes of RAM or the SFR space. Instructions which use direct addressing access the SFR space.

For example, the following direct addressing instruction accesses the SFR at location 0A0H (which is P2).

```
MOV 0A0H, #data
```

Instructions that use indirect addressing access the upper 128 bytes of RAM. For example, the following indirect addressing instruction, where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).

```
MOV @R0, #data
```

Note that stack operations are examples of indirect addressing, so the upper 128 bytes of data RAM are available as stack space.

7. Watchdog Timer (One-time Enabled with Reset-out)

The WDT is intended as a recovery method in situations where the CPU may be subjected to software upsets. The WDT consists of a 14-bit counter and the Watchdog Timer Reset (WDTRST) SFR. The WDT is defaulted to disable from exiting reset. To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, it will increment every machine cycle while the oscillator is running. The WDT timeout period is dependent on the external clock frequency. There is no way to disable the WDT except through reset (either hardware reset or WDT overflow reset). When WDT overflows, it will drive an output RESET HIGH pulse at the RST pin.

7.1 Using the WDT

To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, the user needs to service it by writing 01EH and 0E1H to WDTRST to avoid a WDT overflow. The 14-bit counter overflows when it reaches 16383 (3FFFH), and this will reset the device. When the WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must reset the WDT at least every 16383 machine cycles. To reset the WDT the user must write 01EH and 0E1H to WDTRST. WDTRST is a write-only register. The WDT counter cannot be read or written. When

WDT overflows, it will generate an output RESET pulse at the RST pin. The RESET pulse duration is 98xTOSC, where TOSC = 1/FOSC. To make the best use of the WDT, it should be serviced in those sections of code that will periodically be executed within the time required to prevent a WDT reset.

7.2 WDT During Power-down and Idle

In Power-down mode the oscillator stops, which means the WDT also stops. While in Power-down mode, the user does not need to service the WDT. There are two methods of exiting Power-down mode: by a hardware reset or via a level-activated external interrupt which is enabled prior to entering Power-down mode. When Power-down is exited with hardware reset, servicing the WDT should occur as it normally does whenever the AT89S52 is reset. Exiting Power-down with an interrupt is significantly different. The interrupt is held low long enough for the oscillator to stabilize. When the interrupt is brought high, the interrupt is serviced. To prevent the WDT from resetting the device while the interrupt pin is held low, the WDT is not started until the interrupt is pulled high. It is suggested that the WDT be reset during the interrupt service for the interrupt used to exit Power-down mode.

To ensure that the WDT does not overflow within a few states of exiting Power-down, it is best to reset the WDT just before entering Power-down mode.

Before going into the IDLE mode, the WDIDLE bit in SFR AUXR is used to determine whether the WDT continues to count if enabled. The WDT keeps counting during IDLE (WDIDLE bit = 0) as the default state. To prevent the WDT from resetting the AT89S52 while in IDLE mode, the user should always set up a timer that will periodically exit IDLE, service the WDT, and reenter IDLE mode.

With WDIDLE bit enabled, the WDT will stop to count in IDLE mode and resumes the count upon exit from IDLE.

8. UART

The UART in the AT89S52 operates the same way as the UART in the AT89C51 and AT89C52. For further information on the UART operation, please click on the document link below:

http://www.atmel.com/dyn/resources/prod documents/DOC4316.PDF

9. Timer 0 and 1

Timer 0 and Timer 1 in the AT89S52 operate the same way as Timer 0 and Timer 1 in the AT89C51 and AT89C52. For further information on the timers' operation, please click on the document link below:

http://www.atmel.com/dyn/resources/prod_documents/DOC4316.PDF





10. Timer 2

Timer 2 is a 16-bit Timer/Counter that can operate as either a timer or an event counter. The type of operation is selected by bit $C/\overline{T2}$ in the SFR T2CON (shown in Table 5-2). Timer 2 has three operating modes: capture, auto-reload (up or down counting), and baud rate generator. The modes are selected by bits in T2CON, as shown in Table 10-1. Timer 2 consists of two 8-bit registers, TH2 and TL2. In the Timer function, the TL2 register is incremented every machine cycle. Since a machine cycle consists of 12 oscillator periods, the count rate is 1/12 of the oscillator frequency.

Table 10-1. Timer 2 Operating Modes

RCLK +TCLK	CP/RL2	TR2	MODE
0	0	1	16-bit Auto-reload
0	1	1	16-bit Capture
1	Х	1	Baud Rate Generator
Х	Х	0	(Off)

In the Counter function, the register is incremented in response to a 1-to-0 transition at its corresponding external input pin, T2. In this function, the external input is sampled during S5P2 of every machine cycle. When the samples show a high in one cycle and a low in the next cycle, the count is incremented. The new count value appears in the register during S3P1 of the cycle following the one in which the transition was detected. Since two machine cycles (24 oscillator periods) are required to recognize a 1-to-0 transition, the maximum count rate is 1/24 of the oscillator frequency. To ensure that a given level is sampled at least once before it changes, the level should be held for at least one full machine cycle.

10.1 Capture Mode

In the capture mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 is a 16-bit timer or counter which upon overflow sets bit TF2 in T2CON. This bit can then be used to generate an interrupt. If EXEN2 = 1, Timer 2 performs the same operation, but a 1-to-0 transition at external input T2EX also causes the current value in TH2 and TL2 to be captured into RCAP2H and RCAP2L, respectively. In addition, the transition at T2EX causes bit EXF2 in T2CON to be set. The EXF2 bit, like TF2, can generate an interrupt. The capture mode is illustrated in Figure 10-1.

10.2 Auto-reload (Up or Down Counter)

Timer 2 can be programmed to count up or down when configured in its 16-bit auto-reload mode. This feature is invoked by the DCEN (Down Counter Enable) bit located in the SFR T2MOD (see Table 10-2). Upon reset, the DCEN bit is set to 0 so that timer 2 will default to count up. When DCEN is set, Timer 2 can count up or down, depending on the value of the T2EX pin.



Figure 10-2. Timer 2 Auto Reload Mode (DCEN = 0)

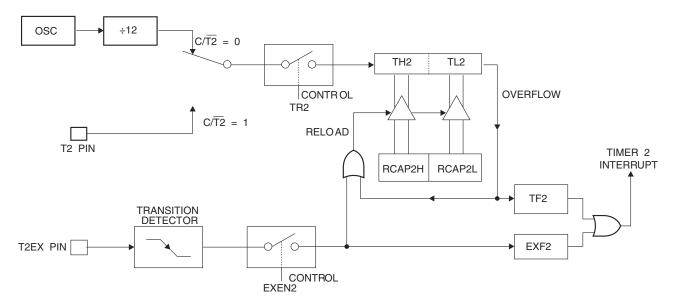
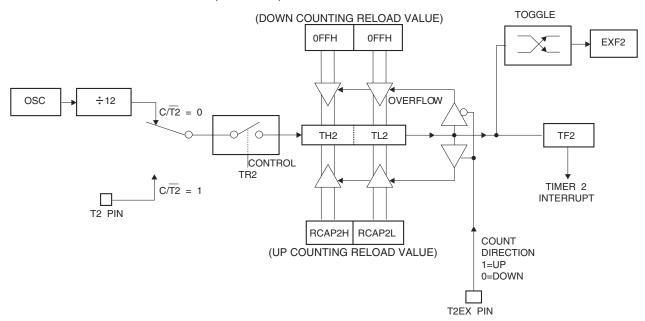


Figure 10-3. Timer 2 Auto Reload Mode (DCEN = 1)



11. Baud Rate Generator

Timer 2 is selected as the baud rate generator by setting TCLK and/or RCLK in T2CON (Table 5-2). Note that the baud rates for transmit and receive can be different if Timer 2 is used for the receiver or transmitter and Timer 1 is used for the other function. Setting RCLK and/or TCLK puts Timer 2 into its baud rate generator mode, as shown in Figure 11-1.

The baud rate generator mode is similar to the auto-reload mode, in that a rollover in TH2 causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2H and RCAP2L, which are preset by software.

The baud rates in Modes 1 and 3 are determined by Timer 2's overflow rate according to the following equation.

Modes 1 and 3 Baud Rates =
$$\frac{\text{Timer 2 Overflow Rate}}{16}$$

The Timer can be configured for either timer or counter operation. In most applications, it is configured for timer operation ($CP/\overline{T2} = 0$). The timer operation is different for Timer 2 when it is used as a baud rate generator. Normally, as a timer, it increments every machine cycle (at 1/12 the oscillator frequency). As a baud rate generator, however, it increments every state time (at 1/2 the oscillator frequency). The baud rate formula is given below.

$$\frac{\text{Modes 1 and 3}}{\text{Baud Rate}} = \frac{\text{Oscillator Frequency}}{32 \times [65536\text{-RCAP2H,RCAP2L})]}$$

where (RCAP2H, RCAP2L) is the content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.

Timer 2 as a baud rate generator is shown in Figure 11-1. This figure is valid only if RCLK or TCLK = 1 in T2CON. Note that a rollover in TH2 does not set TF2 and will not generate an interrupt. Note too, that if EXEN2 is set, a 1-to-0 transition in T2EX will set EXF2 but will not cause a reload from (RCAP2H, RCAP2L) to (TH2, TL2). Thus, when Timer 2 is in use as a baud rate generator, T2EX can be used as an extra external interrupt.

Note that when Timer 2 is running (TR2 = 1) as a timer in the baud rate generator mode, TH2 or TL2 should not be read from or written to. Under these conditions, the Timer is incremented every state time, and the results of a read or write may not be accurate. The RCAP2 registers may be read but should not be written to, because a write might overlap a reload and cause write and/or reload errors. The timer should be turned off (clear TR2) before accessing the Timer 2 or RCAP2 registers.





19. Programming the Flash – Serial Mode

The Code memory array can be programmed using the serial ISP interface while RST is pulled to $V_{\rm CC}$. The serial interface consists of pins SCK, MOSI (input) and MISO (output). After RST is set high, the Programming Enable instruction needs to be executed first before other operations can be executed. Before a reprogramming sequence can occur, a Chip Erase operation is required.

The Chip Erase operation turns the content of every memory location in the Code array into FFH.

Either an external system clock can be supplied at pin XTAL1 or a crystal needs to be connected across pins XTAL1 and XTAL2. The maximum serial clock (SCK) frequency should be less than 1/16 of the crystal frequency. With a 33 MHz oscillator clock, the maximum SCK frequency is 2 MHz.

20. Serial Programming Algorithm

To program and verify the AT89S52 in the serial programming mode, the following sequence is recommended:

- 1. Power-up sequence:
 - a. Apply power between VCC and GND pins.
 - b. Set RST pin to "H".

If a crystal is not connected across pins XTAL1 and XTAL2, apply a 3 MHz to 33 MHz clock to XTAL1 pin and wait for at least 10 milliseconds.

- 2. Enable serial programming by sending the Programming Enable serial instruction to pin MOSI/P1.5. The frequency of the shift clock supplied at pin SCK/P1.7 needs to be less than the CPU clock at XTAL1 divided by 16.
- 3. The Code array is programmed one byte at a time in either the Byte or Page mode. The write cycle is self-timed and typically takes less than 0.5 ms at 5V.
- 4. Any memory location can be verified by using the Read instruction which returns the content at the selected address at serial output MISO/P1.6.
- 5. At the end of a programming session, RST can be set low to commence normal device operation.

Power-off sequence (if needed):

- 1. Set XTAL1 to "L" (if a crystal is not used).
- 2. Set RST to "L".
- 3. Turn V_{CC} power off.

Data Polling: The Data Polling feature is also available in the serial mode. In this mode, during a write cycle an attempted read of the last byte written will result in the complement of the MSB of the serial output byte on MISO.

21. Serial Programming Instruction Set

The Instruction Set for Serial Programming follows a 4-byte protocol and is shown in Table 24-1.

22. Programming Interface - Parallel Mode

Every code byte in the Flash array can be programmed by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

Most major worldwide programming vendors offer support for the Atmel AT89 microcontroller series. Please contact your local programming vendor for the appropriate software revision.

Table 22-1. Flash Programming Modes

				ALE/	EA/						P0.7-0	P2.4-0	P1.7-0
Mode	V _{cc}	RST	PSEN	PROG	V _{PP}	P2.6	P2.7	P3.3	P3.6	P3.7	Data	Address	
Write Code Data	5V	Н	L	(2)	12V	L	Н	Н	Н	Н	D _{IN}	A12-8	A7-0
Read Code Data	5V	Н	L	Н	Н	L	L	L	Н	Н	D _{OUT}	A12-8	A7-0
Write Lock Bit 1	5V	Н	L	(3)	12V	Н	Н	Н	Н	I	Х	х	Х
Write Lock Bit 2	5V	Н	L	(3)	12V	Н	Н	Н	L	L	Х	х	Х
Write Lock Bit 3	5V	Н	L	(3)	12V	Н	L	Н	Н	L	Х	х	Х
Read Lock Bits 1, 2, 3	5V	Н	L	Н	Н	Н	Н	L	Н	L	P0.2, P0.3, P0.4	х	х
Chip Erase	5V	Н	L	(1)	12V	Н	L	Н	L	L	Х	х	Х
Read Atmel ID	5V	Н	L	Н	Н	L	L	L	L	L	1EH	X 0000	00H
Read Device ID	5V	Н	L	Н	Н	L	L	L	L	L	52H	X 0001	00H
Read Device ID	5V	Н	L	Н	Н	L	L	L	L	L	06H	X 0010	00H

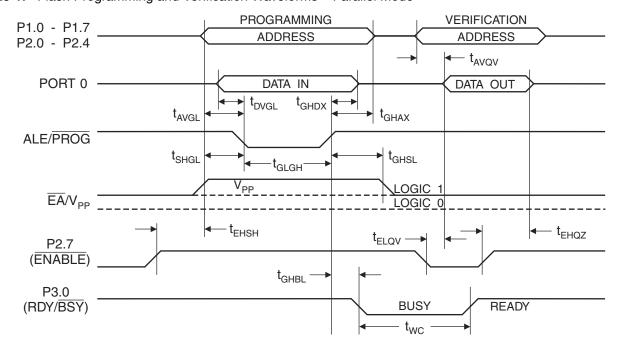
- Notes: 1. Each PROG pulse is 200 ns 500 ns for Chip Erase.
 - 2. Each PROG pulse is 200 ns 500 ns for Write Code Data.
 - 3. Each PROG pulse is 200 ns 500 ns for Write Lock Bits.
 - 4. RDY/BSY signal is output on P3.0 during programming.
 - 5. X = don't care.

23. Flash Programming and Verification Characteristics (Parallel Mode)

 $T_A = 20^{\circ}C$ to 30°C, $V_{CC} = 4.5$ to 5.5V

Symbol	Parameter	Min	Max	Units
V _{PP}	Programming Supply Voltage	11.5	12.5	V
I _{PP}	Programming Supply Current		10	mA
I _{CC}	V _{CC} Supply Current		30	mA
1/t _{CLCL}	Oscillator Frequency	3	33	MHz
t _{AVGL}	Address Setup to PROG Low	48 t _{CLCL}		
t _{GHAX}	Address Hold After PROG	48 t _{CLCL}		
t _{DVGL}	Data Setup to PROG Low	48 t _{CLCL}		
t _{GHDX}	Data Hold After PROG	48 t _{CLCL}		
t _{EHSH}	P2.7 (ENABLE) High to V _{PP}	48 t _{CLCL}		
t _{SHGL}	V _{PP} Setup to PROG Low	10		μs
t _{GHSL}	V _{PP} Hold After PROG	10		μs
t _{GLGH}	PROG Width	0.2	1	μs
t _{AVQV}	Address to Data Valid		48 t _{CLCL}	
t _{ELQV}	ENABLE Low to Data Valid		48 t _{CLCL}	
t _{EHQZ}	Data Float After ENABLE	0	48 t _{CLCL}	
t _{GHBL}	PROG High to BUSY Low		1.0	μs
t _{WC}	Byte Write Cycle Time		50	μs

Figure 23-1. Flash Programming and Verification Waveforms – Parallel Mode



26. Absolute Maximum Ratings*

Operating Temperature55°C to +125°C
Storage Temperature65°C to +150°C
Voltage on Any Pin with Respect to Ground1.0V to +7.0V
Maximum Operating Voltage 6.6V
DC Output Current

*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

27. DC Characteristics

The values shown in this table are valid for $T_A = -40^{\circ}\text{C}$ to 85°C and $V_{CC} = 4.0\text{V}$ to 5.5V, unless otherwise noted.

Symbol	Parameter	Condition	Min	Max	Units
V _{IL}	Input Low Voltage	(Except EA)	-0.5	0.2 V _{CC} -0.1	V
V _{IL1}	Input Low Voltage (EA)		-0.5	0.2 V _{CC} -0.3	V
V _{IH}	Input High Voltage	(Except XTAL1, RST)	0.2 V _{CC} +0.9	V _{CC} +0.5	V
V _{IH1}	Input High Voltage	(XTAL1, RST)	0.7 V _{CC}	V _{CC} +0.5	V
V _{OL}	Output Low Voltage ⁽¹⁾ (Ports 1,2,3)	I _{OL} = 1.6 mA		0.45	V
V _{OL1}	Output Low Voltage ⁽¹⁾ (Port 0, ALE, PSEN)	I _{OL} = 3.2 mA		0.45	V
		$I_{OH} = -60 \mu A, V_{CC} = 5V \pm 10\%$	2.4		V
V_{OH}	Output High Voltage (Ports 1,2,3, ALE, PSEN)	I _{OH} = -25 μA	0.75 V _{CC}		V
		I _{OH} = -10 μA	0.9 V _{CC}		V
		$I_{OH} = -800 \ \mu A, \ V_{CC} = 5V \pm 10\%$	2.4		V
V_{OH1}	Output High Voltage (Port 0 in External Bus Mode)	I _{OH} = -300 μA	0.75 V _{CC}		V
	(refres in External Bas Meas)	Ι _{ΟΗ} = -80 μΑ	0.9 V _{CC}		V
I _{IL}	Logical 0 Input Current (Ports 1,2,3)	V _{IN} = 0.45V		-50	μΑ
I _{TL}	Logical 1 to 0 Transition Current (Ports 1,2,3)	$V_{IN} = 2V$, $V_{CC} = 5V \pm 10\%$		-300	μΑ
ILI	Input Leakage Current (Port 0, EA)	0.45 < V _{IN} < V _{CC}		±10	μA
RRST	Reset Pulldown Resistor		50	300	ΚΩ
C _{IO}	Pin Capacitance	Test Freq. = 1 MHz, T _A = 25°C		10	pF
	Davida Comple Compant	Active Mode, 12 MHz		25	mA
I_{CC}	Power Supply Current	Idle Mode, 12 MHz		6.5	mA
	Power-down Mode ⁽¹⁾	V _{CC} = 5.5V		50	μA

Notes: 1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:

Maximum I per port pin: 10 mA

Maximum I_{OL} per 8-bit port:

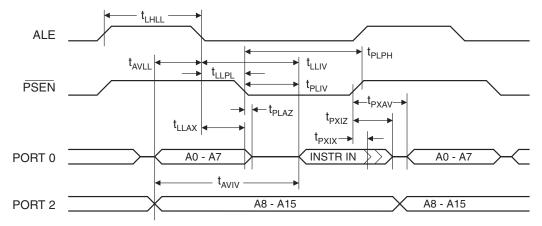
Port 0: 26 mA Ports 1, 2, 3: 15 mA Maximum total I_{OL} for all output pins: 71 mA

If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

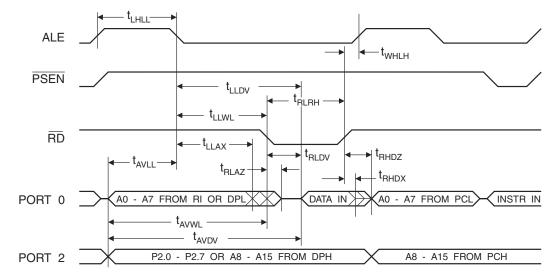
2. Minimum V_{CC} for Power-down is 2V.



29. External Program Memory Read Cycle



30. External Data Memory Read Cycle

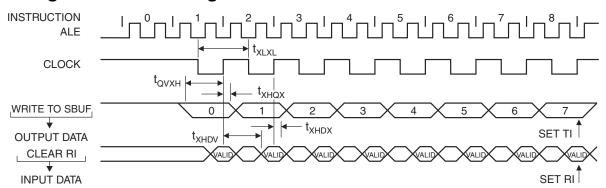


34. Serial Port Timing: Shift Register Mode Test Conditions

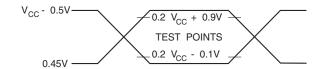
The values in this table are valid for $V_{CC} = 4.0V$ to 5.5V and Load Capacitance = 80 pF.

		12 MH	lz Osc	Variable (
Symbol	Parameter	Min	Max	Min	Max	Units
t _{XLXL}	Serial Port Clock Cycle Time	1.0		12 t _{CLCL}		μs
t _{QVXH}	Output Data Setup to Clock Rising Edge	700		10 t _{CLCL} -133		ns
t _{XHQX}	Output Data Hold After Clock Rising Edge	50		2 t _{CLCL} -80		ns
t _{XHDX}	Input Data Hold After Clock Rising Edge	0		0		ns
t _{XHDV}	Clock Rising Edge to Input Data Valid		700		10 t _{CLCL} -133	ns

35. Shift Register Mode Timing Waveforms

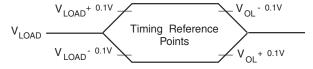


36. AC Testing Input/Output Waveforms⁽¹⁾



Note: 1. AC Inputs during testing are driven at V_{CC} - 0.5V for a logic 1 and 0.45V for a logic 0. Timing measurements are made at V_{IH} min. for a logic 1 and V_{IL} max. for a logic 0.

37. Float Waveforms⁽¹⁾

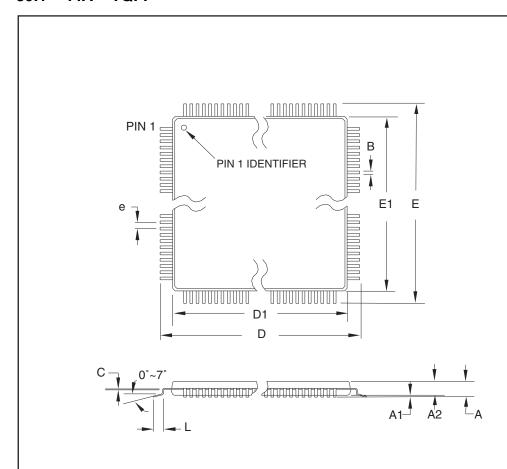


Note: 1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs.



39. Packaging Information

39.1 44A - TQFP



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
А	_	_	1.20	
A1	0.05	_	0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
Е	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
В	0.30	_	0.45	
С	0.09	_	0.20	
L	0.45	_	0.75	
е		0.80 TYP		

Notes:

- 1. This package conforms to JEDEC reference MS-026, Variation ACB.
- 2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
- 3. Lead coplanarity is 0.10 mm maximum.

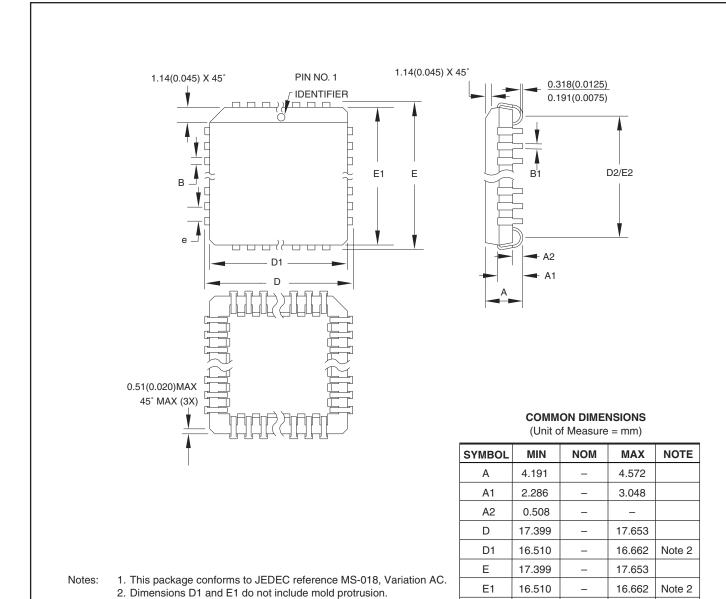
10/5/2001

0005 Ourle and David	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	44A , 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	44A	В





39.2 44J - PLCC



Allowable protrusion is .010"(0.254 mm) per side. Dimension D1

and E1 include mold mismatch and are measured at the extreme

material condition at the upper or lower parting line. 3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

16.002

0.813

0.533

1.270 TYP

0005 Ouch and Dankara	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	44J, 44-lead, Plastic J-leaded Chip Carrier (PLCC)	44J	В

D2/E2

В

В1

е

14.986

0.660

0.330



Headquarters

Atmel Corporation

2325 Orchard Parkway San Jose, CA 95131 USA

Tel: 1(408) 441-0311 Fax: 1(408) 487-2600

International

Atmel Asia

Room 1219 Chinachem Golden Plaza 77 Mody Road Tsimshatsui East Kowloon Hong Kong

Tel: (852) 2721-9778 Fax: (852) 2722-1369 Atmel Europe

France

Le Krebs 8, Rue Jean-Pierre Timbaud BP 309 78054 Saint-Quentin-en-Yvelines Cedex

Tel: (33) 1-30-60-70-00 Fax: (33) 1-30-60-71-11 Atmel Japan

9F, Tonetsu Shinkawa Bldg. 1-24-8 Shinkawa Chuo-ku, Tokyo 104-0033 Japan

Tel: (81) 3-3523-3551 Fax: (81) 3-3523-7581

Product Contact

Web Site

www.atmel.com

Technical Support

mcu@atmel.com

Sales Contact

www.atmel.com/contacts

Literature Requests www.atmel.com/literature

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